

RELIABILITY REPORT  
FOR  
MAX799ESE+  
(MAX796/MAX797/MAX799)  
PLASTIC ENCAPSULATED DEVICES

January 5, 2009

**MAXIM INTEGRATED PRODUCTS**

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## Conclusion

The MAX799ESE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX796/MAX797/MAX799 high-performance, step-down DC-DC converters with single or dual outputs provide main CPU power in battery-powered systems. These buck controllers achieve 96% efficiency by using synchronous rectification and Maxim's proprietary Idle Mode(tm) control scheme to extend battery life at full-load (up to 10A) and no-load outputs. Excellent dynamic response corrects output transients caused by the latest dynamic-clock CPUs within five 300kHz clock cycles. Unique bootstrap circuitry drives inexpensive N-channel MOSFETs, reducing system cost and eliminating the crowbar switching currents found in some PMOS/NMOS switch designs. The MAX796/MAX799 are specially equipped with a secondary feedback input (SECFB) for transformer-based dual-output applications. This secondary feedback path improves cross-regulation of positive (MAX796) or negative (MAX799) auxiliary outputs. The MAX797 has a logic-controlled and synchronizable fixed-frequency pulse-width-modulating (PWM) operating mode, which reduces noise and RF interference in sensitive mobile-communications and pen-entry applications. The SKIP-bar override input allows automatic switchover to idle-mode operation (for high-efficiency pulse skipping) at light loads, or forces fixed-frequency mode for lowest noise at all loads. The MAX796/MAX797/MAX799 are all available in 16-pin DIP and narrow SO packages.

## II. Manufacturing Information

A. Description/Function:	Step-Down Controllers with Synchronous Rectifier for CPU Power
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	ATP Philippines, UTL Thailand
F. Date of Initial Production:	Pre 1997

## III. Packaging Information

A. Package Type:	16-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1701-0175
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	115°C/W
K. Single Layer Theta Jc:	32°C/W

## IV. Die Information

A. Dimensions:	85 X 160 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.4 \times 10^{-9}$$

$$\lambda = 13.4 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the S3 Process results in a FIT Rate of 0.12 @ 25C and 2.1 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The PW42 die type has been found to have all pins able to withstand a HBM transient pulse of +/-600 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX799ESE+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data